ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	nockburn, Illinois. A	Il rights reserved u ntions.	Inder both This d	locument parts, the	is a declarat declarat	tion of the sul encompasses	bstances v all lower	within the manufactu level materials for w	rer listed ite which the m	em. Note: anufactur	: if the item is an as er has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfg Information				
Supplier Information													
Company name* Company unique ID			Uniqu			Unique ID Authority				Response Date*			
onsemi							2024-05-	2024-05-15					
Contact Name Title - Contact				Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Ithorized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product	Product-Env-Stewards@onsemi.com			
Requester Item Number Mf	r Item Number	Mfr Item Name		Ei	ffective Date	e Version	N	Manufacturing Site		Veight*	UOM	Unit Type	
NC	CP81610MNTXG 8 Phase Controll nVidia processor		er with OVR4+ interfac	ce for 20	or 2024-05-15 TH		H6	5 71.		mg	Each		
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	Terminal Base	Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature		e Max Time at Peak	k Temperature Number of Reflow Cycles		les			
Precious metal (e.g. Ag,Au, NiPdAu) (1 Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy Sn)		1		260 C		С	30 sec.		seconds 3			
Comments	5							÷					
evel 1 - maximum time at peak temperature duri	ng soldering is 10-3	0 seconds											
or more information regarding material composition	ition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.03	mg	Supplier	Silicon (Si)	7440-21-3		5.03	mg
Die Attach	0.92	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0552	mg
			Supplier	Silver (Ag)	7440-22-4		0.7498	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0552	mg
			Supplier	Misc.	Proprietary Data		0.0046	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0552	mg
Lead Frame	30.44	mg	Supplier	Silver (Ag)	7440-22-4		0.6088	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0304	mg
			Supplier	Iron (Fe)	7439-89-6		0.6697	mg
			Supplier	Copper (Cu)	7440-50-8		29.1311	mg
Mold Compound-Black	33.0	mg		Epoxy resin	proprietary data		1.65	mg
			Supplier	Phenolic Resin	Proprietary Data		0.759	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.65	mg
			Supplier	Carbon Black (C)	1333-86-4		0.132	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.759	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.05	mg
Plating	1.55	mg	Supplier	Tin (Sn)	7440-31-5		1.55	mg
Wire Bond - Cu	0.22	mg	Supplier	Palladium (Pd)	7440-05-3		0.004	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.2158	mg